L Number	Hits	S arch Text	DB	Time stamp
-	0	(surface near (m unt rm uting r m unted) n ar (package or packaging)).ti,ab,clm. and (l d or (light near miting n ar (diod or d vi))).ti,ab, lm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:27
-	0	(surface near (mount or mouting or mounted) near (package or packaging)).ti,ab,clm. and (led or (light near emitting near (diode or device))).ti,ab,clm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:28
-		(surface near (mount or mouting or mounted) near (package or packaging)) and (led or (light near emitting near (diode or device))) and (seal or sealing or adhesive) and (solder or soldering) and (metal or gold or silver or conductive or conducting) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:28
-	9	(surface near (mount or mounting or mounted)).ti,ab,clm. and (led or (light near emitting near (diode or device))).ti,ab,clm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:30
•	613	(surface near (mount or mounting or mounted)).clm. and (led or (light near emitting near (diode or device))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:30
-	6	(surface near (mount or mounting or mounted)).clm. and (led or (light near emitting near (diode or device))).clm. and ((first or upper or lower or top or bottom or two) near (gold or silver or metal or conductive or conducting) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:34
-	3	(surface near (mount or mounting or m unt d)) near5 (I d or (light n ar emitting near (di de or devic))). Im. and ((first or upp r r I wer or t p or b ttom r tw) n ar (g Id r silver or metal or condu tiv r conducting) n ar layer).clm.	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2004/06/22 15:34

	T	, : 	T	,
-	3	((surface n ar (mount or m unting or	USPAT;	2004/06/22
		m unted)) near5 (led or (light n ar mitting	US-PGPUB;	15:35
		n ar (diod r device)))).clm. and ((first r	EPO; JPO;	
		upper or I wer or top r bott m or two)	DERWENT;	
		near (gold or silver or m tal r onductive	IBM_TDB	
		or c nducting) near layer).clm.		
-	3	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near5 (led or (light near emitting	US-PGPUB;	15:35
		near (diode or device)))).clm. and ((first or	EPO; JPO;	;
		upper or lower or top or bottom or two)	DERWENT;	
		near2 (gold or silver or metal or conductive	IBM_TDB	
		or conducting) near layer).clm.	_	
-	3	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near5 (led or (light near emitting	US-PGPUB;	15:36
		near (diode or device)))).clm. and ((first or	EPO; JPO;	10.00
		upper or lower or top or bottom or two)	DERWENT;	
		near2 (gold or silver or metal or conductive	IBM_TDB	
		or conducting) near2 layer).clm.	15/11/15	
	3	, ,	HODAT.	2004/06/22
-	3	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:36
	1	emitting near (diode or device)))).clm. and	EPO; JPO;	
		((first or upper or lower or top or bottom or	DERWENT;	
		two) near2 (gold or silver or metal or	IBM_TDB	
		conductive or conducting) near2 layer).clm.		
-	4	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:36
		emitting near (diode or device)))).ti,ab,clm.	EPO; JPO;	
		and ((first or upper or lower or top or	DERWENT;	
		bottom or two) near2 (gold or silver or	IBM_TDB	
		metal or conductive or conducting) near2		
		layer).clm.		
-	6	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:38
		emitting near (diode or device)))).ti,ab,clm.	EPO; JPO;	
		and ((first or upper or lower or top or	DERWENT;	
		bottom or two) near2 (gold or silver or	IBM_TDB	
		metal or conductive or conducting) near2	<u>-</u>	
		layer).ti,ab,clm.		
-	6	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:38
		emitting near (diode or device)))).ti,ab,clm.		13:30
		and ((first or second or upper or lower or	EPO; JPO;	
			DERWENT;	
		top or bottom or two) near2 (gold or silver	IBM_TDB	
		or metal or conductive or conducting) near2		
		layer).ti,ab,clm.		
•	952	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:40
		emitting n ar (diode or device)))).ti,ab,clm.	EPO; JP ;	
			DERWENT;	
			IBM_TDB	

				<u>,</u>
 -	16	((surface near (m unt rm unting or	USPAT;	2004/06/22
		mount d)) n ar10 (l d r (light near	US-PGPUB;	15:42
		mitting near (di de r d vice)))).ti,ab,clm.	EPO; JPO;	
		same ((metal or c nductive or ndu ting	DERWENT;	
	İ	r gold r silver) near lay r).ti,ab, lm.	IBM_TDB	
-	1	((surface near (m unt or m unting r	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:45
		emitting near (diode or device)))).clm. same	EPO; JPO;	
		((metal or conductive or conducting or gold	DERWENT;	
		or silver) near layer).clm.	IBM_TDB	
-	2	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:46
		emitting near (diode or device)))).clm. same	EPO; JPO;	
		((electrode or metal or conductive or	DERWENT;	
		conducting or gold or silver) near	IBM_TDB	
		layer).clm.		
-	4	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:47
		emitting near (diode or device)))).clm. same	EPO; JPO;	
		((electrode or metal or conductive or	DERWENT;	
		conducting or gold or silver) near (electrode	IBM_TDB	
		or layer)).clm.		
-	393	((led or (light near emitting near (diode or	USPAT;	2004/06/22
		device)))).clm. and ((second or two or	US-PGPUB;	16:09
		upper or lower or top or bottom) near	EPO; JPO;	
		((electrode or metal or conductive or	DERWENT;	
		conducting or gold or silver) near (electrode	IBM_TDB	
		or layer))).clm.		
-	79	((led or (light near emitting near (diode or	USPAT;	2004/06/22
		device)))).clm. and (substrate near10	US-PGPUB;	16:10
		((second or two or upper or lower or top or	EPO; JPO;	
		bottom) near ((electrode or metal or	DERWENT;	
		conductive or conducting or gold or silver)	IBM_TDB	
		near (electrode or layer)))).clm.		
-	7	(surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)).ti,ab,clm. and ((led or (light near	US-PGPUB;	16:10
		emitting near (diode or device)))).clm. and	EPO; JPO;	
		(substrate near10 ((second or two or upper	DERWENT;	
		or lower or top or bottom) near ((electrode	IBM_TDB	
		or metal or conductive or conducting or		
		gold or silver) near (electrode or		
		layer)))).clm.		
-	291	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	16:13
		emitting))).clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	71	((surface n ar (m unt r mounting or	USPAT;	2004/06/22
		m unt d)) near10 (l d or (light n ar	US-PGPUB;	16:17
		mitting))).clm. and ((surfa e n ar (m unt	EPO; JPO;	
		rm unting rm unted)) n ar10 (led r	DERWENT;	
		(light near mitting))).ab.	IBM_TDB	

	2000	4	HCDAT:	2004/00/20
-	3320	two near metal n ar layer	USPAT; US-PGPUB;	2004/06/22 16:17
			,	10:17
			EPO; JP ; DERWENT;	
			IBM_TDB	
_	29	(two n ar metal near lay r) and (I d or	USPAT;	2004/06/22
-	25	(light near emitting)) and (surface near	US-PGPUB;	16:20
		(mount or mounting or mounted))	EPO; JPO;	10.20
		(mount of mounting of mounted))	DERWENT;	
	İ		IBM_TDB	
_	1	(two near metal near layer).clm. and (led or	USPAT;	2004/06/22
	,	(light near emitting)) and (surface near	US-PGPUB;	16:20
		(mount or mounting or mounted))	EPO; JPO;	10.20
		(mount of mounting of mountou)	DERWENT;	
			IBM_TDB	
	10	(two near (silver or gold or conductive or	USPAT;	2004/06/22
		conducting or electrode or metal) near	US-PGPUB;	16:22
		layer).clm. and (led or (light near emitting))	EPO; JPO;	,
		and (surface near (mount or mounting or	DERWENT;	
		mounted))	IBM_TDB	
-	2285	(two near2 (silver or gold or conductive or	USPAT;	2004/06/22
		conducting or electrode or metal) near	US-PGPUB;	16:23
		layer) near10 (insulate or insulated or	EPO; JPO;	
		insulating or insulation or isolate or	DERWENT;	:
		isolated or isolating or isolation)	IBM_TDB	
-	280	((two near2 (silver or gold or conductive or	USPAT;	2004/06/22
		conducting or electrode or metal) near	US-PGPUB;	16:24
		layer) near10 (insulate or insulated or	EPO; JPO;	
		insulating or insulation or isolate or	DERWENT;	
		isolated or isolating or isolation)).clm.	IBM_TDB	
-	7371	(((second or first or upper or lower or top or	USPAT;	2004/06/22
		bottom or two) near2 (silver or gold or	US-PGPUB;	16:26
		conductive or conducting or electrode or	EPO; JPO;	
	1	metal) near layer) near10 (insulate or	DERWENT;	
		insulated or insulating or insulation or	IBM_TDB	
		isolate or isolated or isolating or		
		isolation)).clm.		
-	1779	(((second or first or upper or lower or top or	USPAT;	2004/06/22
		bottom or two) near2 (silver or gold or	US-PGPUB;	16:25
		conductive or conducting or electrode or	EPO; JPO;	
		metal) near layer) near10 (insulate or	DERWENT;	
		insulated or insulating or insulation or	IBM_TDB	
		isolate or isolated or isolating or isolation)		
	_	near10 substrate).clm.		
-	2	((((second or first or upper or lower or top	USPAT;	2004/06/22
		or bottom or two) near2 (silver or gold or	US-PGPUB;	16:28
		conductive or conducting or electrode or	EPO; JPO;	
		metal) near layer) n ar10 (insulate or	DERWENT;	
		insulated or insulating rinsulatin or	IBM_TDB	
		isolat ris lated or isolating r		
		isolati n)).clm. same (substrat) same (l d		
		r (light near emitting)) same (surfa n ar		
L		(m unt or mounting r mounted))).clm.	L	